

## RT/duroid® 6002 High Frequency Laminates

### Features:

- Low loss for excellent high frequency performance.
- Tight  $\epsilon_r$  and thickness control.
- Excellent electrical and mechanical properties.
- Extremely low thermal coefficient of dielectric constant.
- In-plane expansion coefficient matched to copper.
- Low Z-axis expansion.
- Low outgassing; Ideal for space applications.

### Some Typical Applications:

- Phase Array Antennas
- Ground Based and Airborne Radar Systems
- Global Positioning System Antennas
- Power Backplanes
- High Reliability Complex Multilayer Circuits
- Commercial Airline Collision Avoidance Systems
- Beam Forming Networks



RT/duroid® 6002 microwave material is the first low loss and low dielectric constant laminate to offer superior electrical and mechanical properties essential in designing complex microwave structures which are mechanically reliable and electrically stable.

The thermal coefficient of dielectric constant is extremely low from -55°C to +150°C (-67°F to 302°F) which provides the designers of filters, oscillators and delay lines the electrical stability needed in today's demanding applications.

A low Z axis coefficient of thermal expansion (CTE) ensures excellent reliability of plated through-holes. RT/duroid 6002 materials have been successfully temperature cycled (-55°C to 125°C [-67°F to 257°F]) for over 5000 cycles without a single via failure.

Excellent dimensional stability (0.2 to 0.5 mils/inch) is achieved by matching the X and Y coefficient of expansion to copper. This often eliminates double etching to achieve tight positional tolerances.

The low tensile modulus (X,Y) greatly reduces the stress applied to solder joints and allows the expansion of the laminate to be constrained by a minimum amount of low CTE metal (6 ppm/°C) further increasing surface mount reliability.

¼ oz. to 2 oz./ft.<sup>2</sup> electrodeposited copper, or ½ oz. to 2 oz./ft.<sup>2</sup> rolled copper foil may be specified as cladding on dielectric thicknesses from 0.005" to 0.120" (0.13 to 3.05mm). RT/duroid 6002 laminate is also available clad with aluminum, brass, or copper plates.

Applications particularly suited to the unique properties of RT/duroid 6002 material include flat and non-planar structures such as antennas, complex multilayer circuits with interlayer connections, and microwave circuits for aerospace designs in hostile environments. RT/duroid 6002 laminates have Underwriters Laboratories recognition under classification 94V-0 (Vertical Flammability Test).

## Typical Values

## RT/duroid® 6002 High Frequency Laminates

PROPERTY	TYPICAL VALUE[2]	DIRECTION	UNITS[1]	CONDITIONS	TEST METHOD
Dielectric Constant, $\epsilon_r$	2.94 ± 0.04 (Y Spec) 2.92±-0.04	Z	--	10 GHz/23°C	IPC-TM-650, 2.5.5.5
Dissipation Factor, Tan $\delta$	0.0012	Z	--	10 GHz/23°C	IPC-TM-650, 2.5.5.5
Thermal Coefficient of $\epsilon_r$	+12	Z	ppm/°C	10 GHz/1-100°C	IPC-TM-650, 2.5.5.5
Volume Resistivity	10 <sup>6</sup>	Z	Mohm cm	A	ASTM D257
Surface Resistivity	10 <sup>7</sup>	Z	Mohm	A	ASTM D257
Tensile Modulus	828 (120)	X,Y	MPa (kpsi)	23°C	ASTM D638
Ultimate Stress	6.9 (1.0)	X,Y	MPa (kpsi)		
Ultimate Strain	7.3	X,Y	%		
Compressive Modulus	2482 (360)	Z	MPa (kpsi)		ASTM D638
Moisture Absorption	0.1 0.13 max	---	%	D23/24 D48/50	IPC-TM-650 2.6.2.1 ASTM D570
Thermal Conductivity	0.60	---	W/m/K	80°C	ASTM C518
Coefficient of Thermal Expansion	16 24	X,Y Z	ppm/°C	(10K/min)	ASTM D3386
Td	500		°C TGA		ASTM D3850
Density	2.1		gm/cm <sup>3</sup>		ASTM D792
Specific Heat	0.93 (0.22)	---	J/g/K (BTU/lb/°F)	----	Calculated
Copper Peel	8.9 (1.6)		lbs/in (N/mm)		IPC-TM-650, 2.4.8
Flammability	94V-0				UL
Lead-Free Process Compatible	Yes				

[1] S1 units given first, with other frequently used units in parentheses.

[2] References: Internal TRs 3824, 5016, 5017, 5035. Tests were at 23°C unless otherwise noted.

Typical Values should not be used for specification limits.

STANDARD THICKNESS:	STANDARD PANEL SIZE:	STANDARD COPPER CLADDING:
0.005" (0.127mm) 0.010" (0.254mm) 0.020" (0.508mm) 0.030" (0.762mm) 0.060" (1.524mm) 0.120" (3.048mm)	18" X 12" (457 X 305mm) 18" X 24" (457 X 610mm)	¼ oz. (8 µm) electrodeposited copper foil. ½ oz. (17µm), 1 oz. (35µm), 2 oz. (70µm) electrodeposited and rolled copper foil.  Unclad material 0.020" or greater is available. Thick metal claddings are available. Contact customer service for more information.

CONTACT INFORMATION:			
USA:	Rogers Advanced Circuit Materials - ISO 9000:2000 certified	Tel: 480-961-1382	Fax: 480-961-4533
Belgium:	Rogers NV - Gent - ISO 9000:2000 certified	Tel: +32-9-2353611	Fax: +32-9-2353658
Japan:	Rogers Japan Inc.	Tel: 81-3-5200-2700	Fax: 81-3-5200-0571
Taiwan:	Rogers Taiwan Inc.	Tel: 886-2-86609056	Fax: 886-2-86609057
Korea:	Rogers Korea Inc.	Tel: 82-31-716-6112	Fax: 82-31-716-6208
Singapore:	Rogers Technologies Singapore Inc.	Tel: 65-747-3521	Fax: 65-747-7425
China:	Rogers (Shanghai) International Trading Co., Ltd	Tel: 86-21-63916088	Fax: 86-21-63915060

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